



Advancements in Optical Interconnection and Optical Sensing: Emerging Technologies and Applications

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Message from the Guest Editors

We are pleased to announce the forthcoming Special Issue on "Advancements in Optical Interconnection and Optical Sensing: Emerging Technologies and Applications." This Issue aims to provide a comprehensive view of the latest research on optical interconnection and sensing technologies, along with their diverse applications.

The topics of interest for this Special Issue include, but are not limited to, the following: optical switches, photonics information processing, lidars, optical phase arrays, artificial intelligence, optical neural networks, programmable photonic circuits, nanophotonics, photonics inverse design, surface plasmon resonance sensors, optical fiber sensors, as well as chemical, electrochemical, and biological sensors.

Researchers from academia and industry are invited to contribute to this Special Issue by submitting their latest research in the form of a full-text article or review. The aim of this Special Issue is to promote innovative and original research, and to advance the field of optical sensing and interconnection technologies, while exploring their integration with emerging technologies.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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